



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D  <i>* : Required Field</i>

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2015-10-08
<b>Contact Name *</b>	Refer to "Supplier Comment" section	<b>Contact Title</b>	Refer to "Supplier Comment" section
<b>Contact Phone *</b>	Refer to "Supplier Comment" section	<b>Contact Email *</b>	Refer to "Supplier Comment" section
<b>Authorized Representative *</b>	Rossana Bonaccorso	<b>Representative Title</b>	IPD MD Champion
<b>Representative Phone *</b>	Refer to "Supplier Comment" section	<b>Representative Email *</b>	Refer to "Supplier Comment" section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**


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Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	RWSX*LA17AB6	A	Z4XA	2015-10-08
Amount	UoM	Unit type	ST ECOPACK Grade	
216.20	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
NAC	NAC	NAC		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	4.6 - 4.6 - 3.5	3	Through-hole	
Comment	Package: TO 92;MDF valid for LM317LZ; LM317LZ-AP; LM317LZ-TR			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-15th June 2015				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	RWSX*LA17AB6						
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)	
Die	Other inorganic materials	1.804	mg	supplier	die	Silicon (Si)	7440-21-3		1.771	mg	981707	8191	
				supplier	metallization	Aluminium (Al)	7429-90-5		0.015	mg	8315	69	
				supplier	Passivation	Silicon Nitride	12033-89-5		0.008	mg	4435	37	
Leadframe	Copper & its alloys	100.492	mg	supplier	Passivation	Silicon Oxide	7631-86-9		0.01	mg	5543	46	
				supplier	Alloy	Copper(Cu)	7440-50-8		100.388	mg	998965	464329	
				supplier	Alloy	Phosphorus(P)	12185-10-3		0.031	mg	308	143	
Die attach	Other inorganic materials	0.166	mg	supplier	Alloy	Iron(Fe)	7439-89-6		0.073	mg	726	338	
				supplier	Solder	Silver(Ag)	7440-22-4		0.116	mg	698795	537	
				supplier	Solder	Bisphenol F type epoxy resin resin	9003-36-5		0.034	mg	204819	157	
Bonding wire	Other inorganic materials	0.964	mg	supplier	Solder	Phenol derivative	Proprietary		0.008	mg	48193	37	
				supplier	Solder	Di propylene glycol mono methyl etherthocym	34590-94-8		0.008	mg	48193	37	
				supplier	Bonding wire	Copper(Cu)	7440-50-8		0.964	mg	1000000	4459	
Encapsulation	Other inorganic materials	110.855	mg	supplier	Mold compound	Silica Crystal	14808-60-7		94.225	mg	849984	435823	
				supplier	Mold compound	Cristobalite	14464-46-1		1.106	mg	9977	5116	
				supplier	Mold compound	Epoxy Resin	Proprietary		11.172	mg	100780	51674	
				supplier	Mold compound	Phenol Resin	Proprietary		2.58	mg	23274	11933	
				supplier	Mold compound	AntimonyTrioxide	1309-644		1.702	mg	15353	7872	
Connections coating	Solder	1.919	mg	supplier	Mold compound	Carbon Black	1333-86-4		0.07	mg	631	324	
				supplier	solder alloy	Tin (Sn)	7440-31-5		1.919	mg	1000000	8876	